

POLISHING METHOD

ABSTRACT OF THE DISCLOSURE

A polishing method for polishing a wafer by use of a polishing unit having a spindle with a polishing tool, the polishing tool having a disk-shaped base and an annular polishing layer that is fixed to one surface of the base and that includes an opening being located at a central portion in a diameter direction of the base and having a predetermined diameter, a maximum width of an effective polishing region of the polishing layer in a radial direction of the base being smaller than the radius of the wafer and the radius of the wafer being smaller than the diameter of the opening, the method includes polishing the wafer in such a manner that a part of a peripheral edge of the wafer protrudes from a periphery of the polishing layer.

[Figure 2]